

Amendments to the Abstract:

Please replace the Abstract at page 20 of the specification with the following amended paragraph:

ABSTRACT OF THE DISCLOSURE

A ~~system and~~ method for cleaning and drying semiconductor wafers improves device yield by providing more advanced control of the ratio of drying fluid to cleaning fluid, for example the ratio of N2 vapor to IPA vapor. In addition, a quick drain process is employed to improve process throughput, and to further improve particle and watermark removal during the cleaning and drying steps.